

Features

- Transient Protection For Data&Power Lines to IEC 61000-4-2(ESD) 30kV(air),30kV(contanct)
- ESD protection of one line.
- Max. peak pulse power: PPP = 240W at tp = 8/20us.

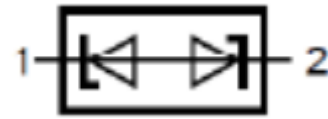


Typical Applications

- LIN-bus.
- ESD protection applications.

Mechanical Data

- Case: SOD-323.
- Molding compound, UL flammability classification rating 94V-0.
- Terminals: Tin plated leads, solderable per MIL-STD-202, Method 208.



GESD1242VB3

SOD-323

Ordering Information

Part Number	Package	Shipping	Marking Code
GESD1242VB3□	SOD-323	3000/Tape Reel	1242

□: none is for Lead Free package;

“G” is for Halogen Free package.

Maximum Ratings (@T_A=25°C unless otherwise specified)

Characteristic	Symbol	Value	Units
Peak pulse power (tp = 8/20μs)	P _{PK}	240	W
ESD according to IEC61000-4-2 air	V _{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge	V _{ESD}	±30	KV

Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance Junction to Ambient Air	R _{θJA}	545	°C/W
Thermal Resistance Junction to Case	R _{θJC}	454	°C/W
Thermal Resistance Junction to Lead	R _{θJL}	405	°C/W
Junction temperature	T _J	125	°C
Storage temperature range	T _{STG}	-55 to+150	°C

Electrical Characteristics (@ $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	V_{RWM}	Pin 1 to Pin 2 Pin 2 to Pin 1	-	-	12 42	V
Reverse breakdown voltage	V_{BR}	$I_R=1\text{mA}$ Pin 1 to Pin 2 Pin 2 to Pin 1	13.3 43	-	17 49	V
Reverse leakage current	I_R	Pin 1 to Pin 2, $V_{RWM}=12\text{V}$ Pin 2 to Pin 1, $V_{RWM}=42\text{V}$	-	-	0.5 0.5	μA
Clamping voltage	V_C	Pin 1 to Pin 2	-	-	20	V
		$I_{PP}=1\text{A}$	-	-	25	
		$I_{PP}=12\text{A}$	-	-	53	V
		Pin 2 to Pin 1	-	-	62	
Diode capacitance	C_d	$V_R=0\text{V}, f=1\text{MHz}$	-	-	30	pF

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

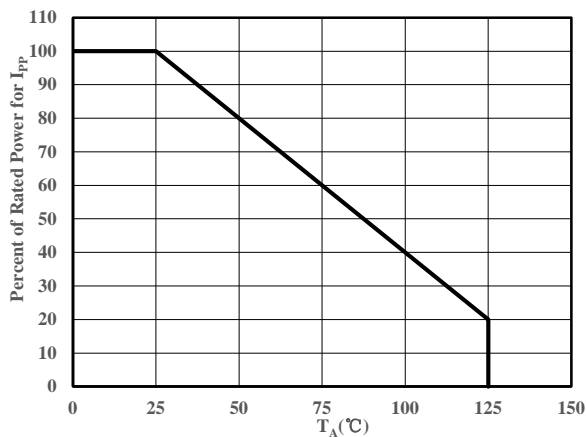


Fig1. Power Derating Curve

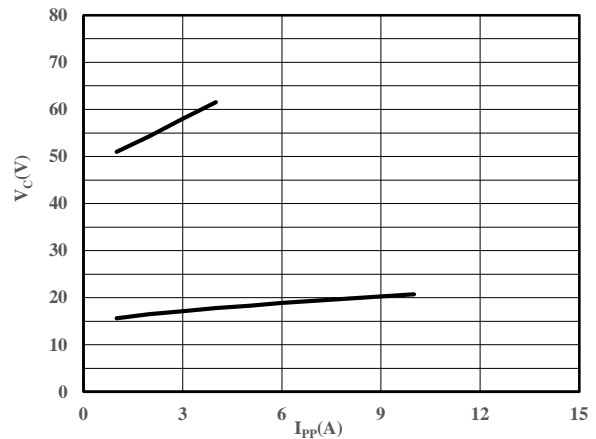


Fig2. Clamping Voltage vs. Peak Pulse Current

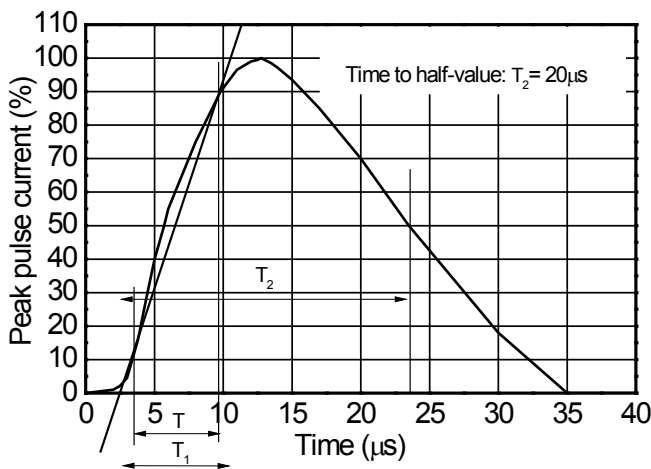


Fig3. 8/20 μs waveform per IEC61000-4-5

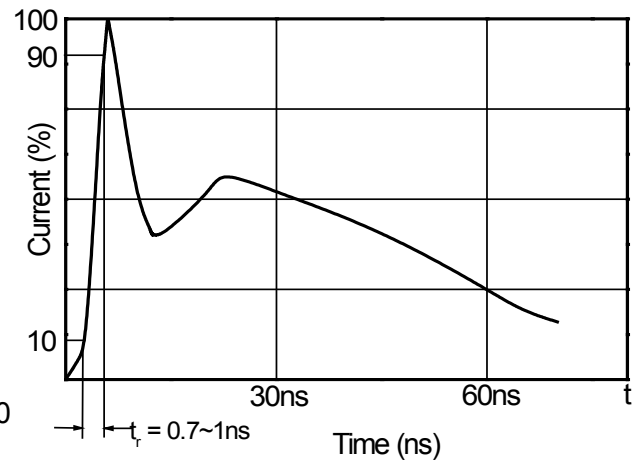
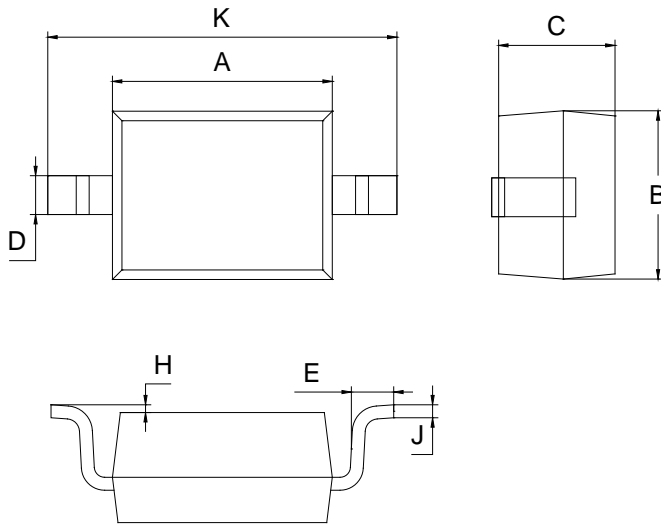


Fig4. ESD pulse waveform according to IEC61000-4-2

Package Outline Dimensions(unit:mm)

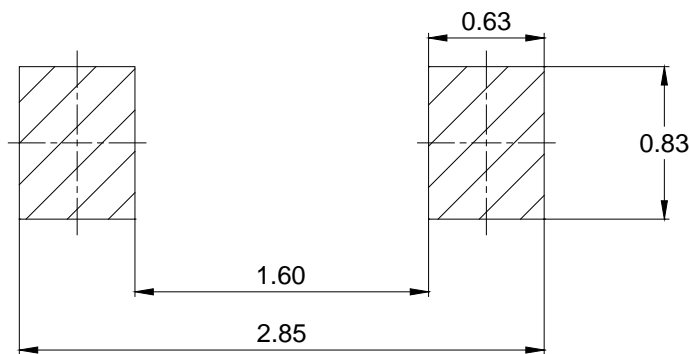
SOD-323



SOD-323		
Dim	Min	Max
A	1.60	1.80
B	1.20	1.40
C	0.80	0.90
D	0.25	0.35
E	0.22	0.42
H	0.02	0.10
J	0.05	0.15
K	2.55	2.75

Mounting Pad Layout(unit:mm)

SOD-323



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